SANGDEST MICROELECTRONICS

20CWQ10FN

Technical Data *Green Products*

Data Sheet N1566, Rev. -

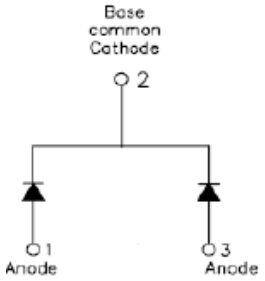
20CWQ10FN SCHOTTKY RECTIFIER

Applications:

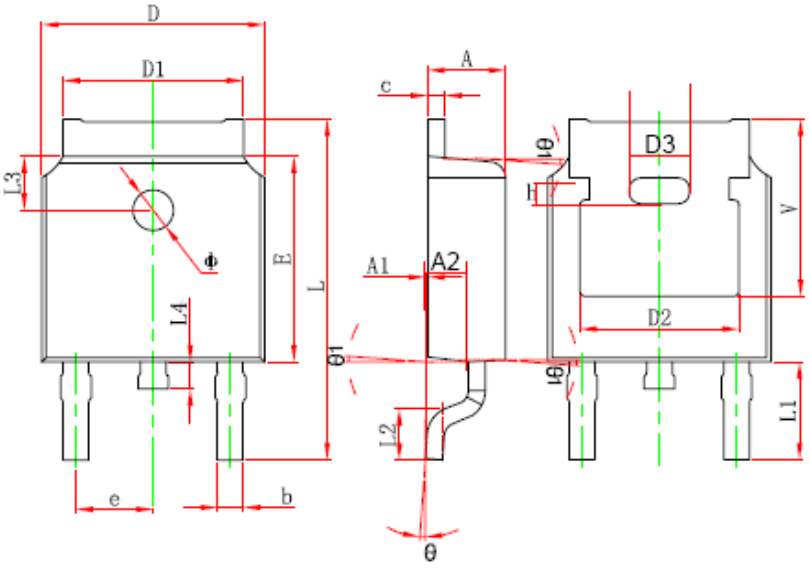
- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Features:

- 175 °C T_J operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb − Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request



Mechanical Dimensions (In mm / Inches) and Marking:



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.380	0.087	0.094
A1	0.000	0.100	0.000	0.004
b	0.710	0.810	0.028	0.032
c	0.460	0.560	0.018	0.022
D	6.500	6.700	0.256	0.264
D1	5.130	5.460	0.202	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
A2	0.910	1.110	0.036	0.044
V	5.350 REF.		0.211 REF.	
D3	1.778REF.		0.070REF.	
h	0.762REF.		0.030REF.	
θ1	7°		7°	

DPAK

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Marking Diagram:



Where XXXXX is YYWWL

20	= Forward Current (20A)
CW	= Configuration
Q	= Device Type
100	= Reverse Voltage (100V)
FN	= Package type
SSG	= SSG
YY	= Year
WW	= Week
L	= Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Ordering Information:

Device	Package	Shipping
20CWQ10FN	DPAK (Pb-Free)	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	V_{RWM}	-	100	V
Average Forward Current	$I_{F(AV)}$	50% duty cycle @T_C =159°C, rectangular wave form	20	A
Peak One Cycle Non-Repetitive Surge Current (per leg)	I_{FSM}	8.3 ms, half Sine pulse	100	A

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Electrical Characteristics:

Characteristics	Symbol	Condition	Max.	Units
Forward Voltage Drop (per leg) *	V_{F1}	@ 10A, Pulse, T_J = 25 °C	0.85	V
	V_{F2}	@ 10A, Pulse, T_J = 125 °C	0.75	V
Reverse Current at DC condition (per leg)	I_{R1}	@V_R = rated V_R T_J = 25 °C	1.0	mA
Reverse Current (per leg) *	I_{R2}	@V_R = rated V_R T_J = 125 °C	6.0	mA
Junction Capacitance (per leg)	C_T	@V_R = 5V, T_C = 25 °C f_{SIG} = 1MHz	250	pF
Typical Series Inductance (per leg)	L_S	Measured lead to lead 5 mm from package body	8.0	nH
Voltage Rate of Change	dv/dt	-	10,000	V/µs

Pulse Width < 300µs, Duty Cycle <2%

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T_J	-	-55 to +175	°C
Storage Temperature	T_{stg}	-	-55 to +175	°C
Maximum Thermal Resistance Junction to Case (per leg)	$R_{\theta JC}$	DC operation	3.5	°C/W
Approximate Weight	wt	-	0.39	g
Case Style	DPAK			

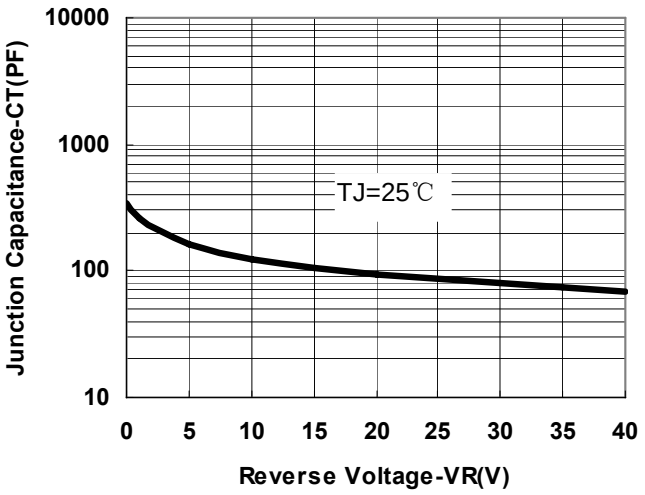

Fig.1-Typical Junction Capacitance

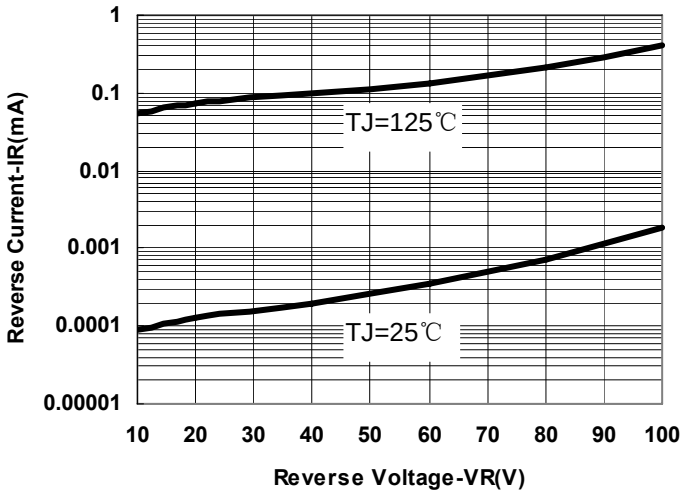

Fig.2-Typical Reverse Characteristics

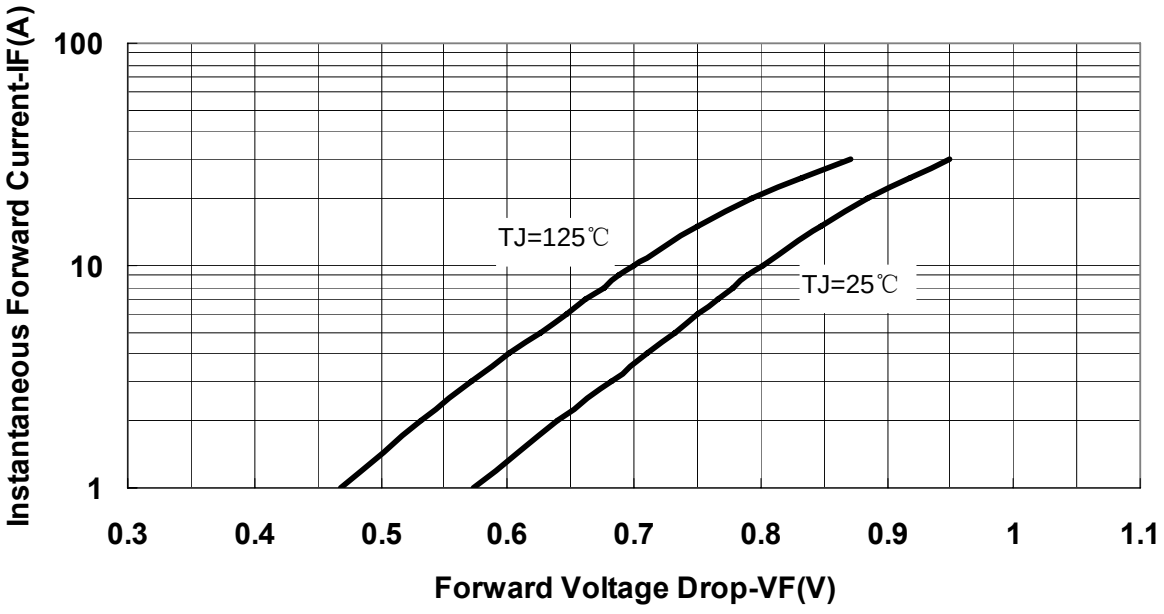

Fig.3-Typical Instantaneous Forward Voltage Characteristics

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